

ADVANCE MODULES GROUP LIMITED
(Company Registration No. 200401776E)

**JOINT DEVELOPMENT AGREEMENT AND A PATENT LICENSE AGREEMENT WITH
ADVANPACK SOLUTIONS PTE LTD**

The Board of Directors of Advance Modules Group Limited (the "Company" or "AMG") wishes to announce that the Company has on 3 April 2008 entered into a Joint Development Agreement and a Patent License Agreement with Advanpack Solutions Pte Ltd ("APS") for the development of memory application utilizing APS patented Pillar bumping and packaging technologies. The agreements shall be collectively known as Collaboration.

Salient Terms of the Collaboration

APS owns amongst others, Flip Chip Memory Modules Technology which is a non-encapsulated semiconductor memory device, bumped with Pillar Bump. Pursuant to the Joint Development Agreement, APS will provide the license, technical know-how and facilities for Copper Pillar Bump technology to AMG for the production of AM branded memory modules as well as the production for OEM customers. In return, AMG will contribute its new Chip Scale Packaging (CSP) technology together with the technical know-how and facilities for APS to explore the manufacturing of APS's Paper Leadframe products.

Pursuant to the Patent License Agreement, APS shall grant to AMG and its subsidiaries a worldwide, non-exclusive, non-transferable license to the necessary patent rights owned by APS related to the Copper Pillar Bump, Flip Chip Memory modules and Paper Leadframe in consideration for license fees based on the number of modules produced.

Rationale for the Collaboration

With this Collaboration, AMG is considered as the first Company in the world to use the CSP technology and the paper leadframe technology to develop the new memory products. The Company believes that's the Collaboration will provide a strategic opportunity to spur AMG to a higher level through further expansion in its range of value added services and product innovation opportunities. This is inline with the Company's expansion upstream in the vertical value chain as a fully integrated memory product manufacturer.

Thus far, the Company has invested approximately USD12 million in this new CSP technology at its IC packaging facility in Shanghai, Advance Modules Semiconductor Packaging (Shanghai) Co. Ltd, which will facilitate, amongst others, kick start the development of Paper Leadframe application for the Memory products. There will not be major capital expenditure for the Copper Pillar Bumping technology as the Collaboration involves a mutual benefit of the access to the facilities between the Company and APS.

Information on APS

APS, an associated company of Singapore listed Advanced Systems Automation Limited, is a flip-chip assembly service and technology-licensing provider with a flip-chip assembly facilities in Singapore. It develops proprietary technology and provides innovative and integrated flip chip solutions to companies that manufacture semiconductors. The company has licensed pillar bump technology to more than 10 companies, including top semiconductor packaging subcontractor; e.g. Amkor, SPIL, Nepes. It also has joint-venture facilities both in Malaysia with Unisem and Shanghai with JCET (the largest bumping and wafer level CSP producer in China). The shareholders of APS are Advanced Systems Automation Ltd, EDB Investments Pte Ltd, JC Investments Pte Ltd, AP Growth Fund L.P, H&Q Asia Venture II Ltd, PLE Investments Pte Ltd and Mezzanine Investment Holding Ltd.

Substantial Shareholders and Director's Interest

None of the substantial shareholders or directors of the Company has any interest, direct or indirect in the Collaboration.

Financial Impact

The Collaboration is not expected to have any significant impact on the net tangible assets. However, it is expected to contribute positively to the earnings for the financial year ending 31 December 2008.

BY ORDER OF THE BOARD
ADVANCE MODULES GROUP LIMITED

KEE CHIT HUEI
EXECUTIVE DIRECTOR

8 APRIL 2008